

Title (en)  
METHOD FOR MOUNTING AN ELECTRICAL COMPONENT, WHEREIN A HOOD IS USED, AND HOOD SUITABLE FOR USE IN SAID METHOD

Title (de)  
VERFAHREN ZUM MONTIEREN EINES ELEKTRISCHEN BAUELEMENTS, BEI DER EINE HAUBE ZUM EINSATZ KOMMT, UND ZUR ANWENDUNG IN DIESEM VERFAHREN GEEIGNETE HAUBE

Title (fr)  
PROCÉDÉ DE MONTAGE D'UN COMPOSANT ÉLECTRIQUE EN UTILISANT UN CAPOT ET CAPOT ADAPTÉ POUR ÊTRE EMPLOYÉ DANS CE PROCÉDÉ

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Application  
**EP 15715699 A 20150330**

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Abstract (en)  
[origin: WO2015150311A1] The invention relates to a method for mounting an electrical component (12) on a substrate (13). According to the invention, the joining is simplified by using a hood (11), wherein in said hood, a contacting structure (16) is provided, and upon placing the hood (11) at different joining levels (28, 29), said contacting structure is simultaneously joined with an additional material (35). The invention further relates to a hood that is suited for use in said method. According to the invention, the hood is made of a material that can be thermally softened or thermally hardened, preferably a resin or a thermoplastic synthetic material. Preferably, the hood is heated during the joining of the connections such that the hood may be plastically deformed. Beneficially, in this way, tolerances are compensated for during the joining process such that a reliable formation of all of the connections can occur. Furthermore, by means of the hood, a necessary joining pressure can be built up, such as is required, for example, in diffusion bonding or sinter bonding of the electrical contacts.

IPC 8 full level  
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CPC (source: CN EP US)  
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